

v00.0511



GaAs MMIC SMT SINGLE BALANCED MIXER, 1.7 - 3.0 GHz

Typical Applications

The HMC272AMS8 / HMC272AMS8E is ideal for:

- Up or Down Converter for PCS
- W-CDMA
- 2.4 GHz ISM
- MMDS

Features

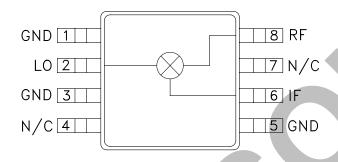
RoHS Compliant Product

Ultra Small Package: MSOP8

LO / RF Isolation: 32 dB

Input IP3: +20 dBm

Functional Diagram



General Description

The HMC272AMS8 & HMC272AMS8E are general purpose ultra miniature single balanced mixers in 8 lead plastic surface mount Mini Small Outline Packages (MSOP). This passive MMIC mixer is constructed of GaAs Schottky diodes and a novel planar transformer balun on the chip. The RF port is balanced via the MMIC balun while the LO port is connected directly to the diodes. The consistent MMIC performance will improve system operation and assure regulatory compliance.

Electrical Specifications, $T_A = +25^{\circ}$ C, As a Function of IF Frequency

Parameter		LO = +10 dBm IF = 100 MHz		LO = +10 dBm IF = 400 MHz			Units
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Frequency Range, RF & LO		2 - 3			1.7 - 2.8		GHz
Frequency Range, IF		DC - 0.8			DC - 0.8		GHz
Conversion Loss		9	10.5		9	11	dB
Noise Figure (SSB)		9	10.5		9	11	dB
LO to RF Isolation	22	30		24	32		dB
LO to IF Isolation	12	20		11	18		dB
IP3 (Input)	17	21		16	20		dBm
1 dB Compression (Input)	8	11		7	10		dBm

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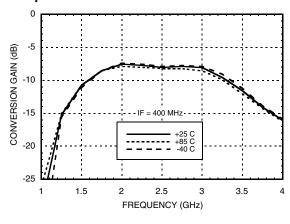
GaAs MMIC SMT SINGLE



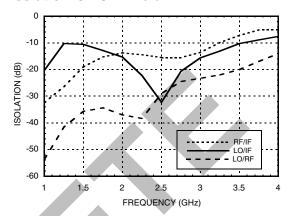
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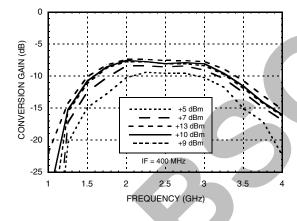
Conversion Gain vs. Temperature @ LO = +10 dBm



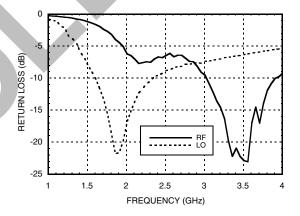
Isolation @ LO = +10 dBm



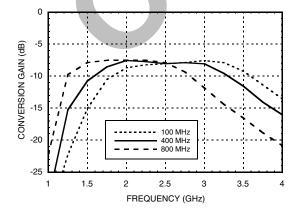
Conversion Gain vs. LO Drive



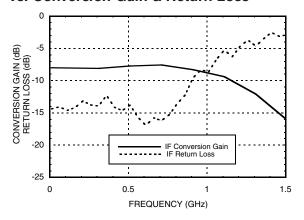
Return Loss @ LO = +10 dBm



Conversion Gain vs. IF Frequency



IF Bandwidth @ LO = +10 dBm vs. Conversion Gain & Return Loss



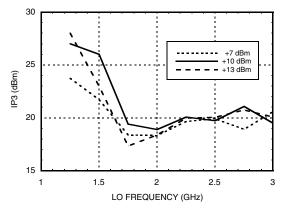


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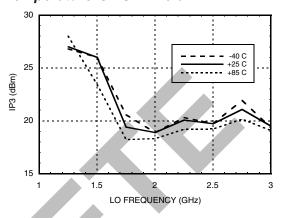


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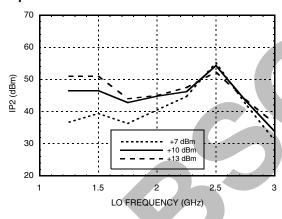
Input IP3 vs. LO Drive



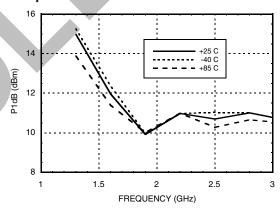
Input IP3 vs. Temperature @ LO = +10 dBm



Input IP2 vs. LO Drive



P1dB vs. Temperature @ LO = +10 dBm





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MxN Spurious Outputs

	nLO				
mRF	0	1	2	3	4
0	XX	-11	-6	5	19
1	7	0	37	27	38
2	53	64	62	46	72
3	83	>85	>85	>85	>85
4	>85	>85	>85	>85	>85

RF = 2.6 GHz @ -10 dBm LO = 2.2 GHz @ +13 dBm All values in dBc relative to the IF

Harmonics of LO

		nLO Spur	at RF Port	
LO Frequency (GHz)	1	2	3	4
1.5	37	14	36	41
1.7	35	12	37	48
1.9	35	13	43	49
2.1	43	16	42	49
2.3	36	19	37	49
2.5	29	23	36	50

LO = +10 dBm Values in dBc below input LO level measured at the RF port.

Absolute Maximum Ratings

LO Drive +27 dBm Storage Temperature -65 to +150 °C Operating Temperature -40 to +85 °C	RF / IF Input	+13 dBm
	LO Drive	+27 dBm
Operating Temperature -40 to +85 °C	Storage Temperature	-65 to +150 °C
	Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM) Class 1A	ESD Sensitivity (HBM)	Class 1A



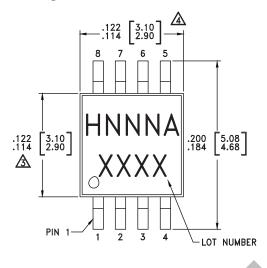
ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

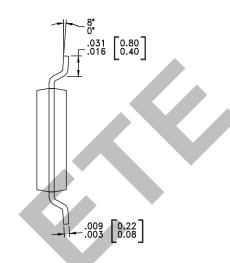
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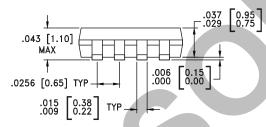


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Outline Drawing







NOTES

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- \triangle DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number		Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC272AMS8		Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H272A XXXX
HMC272AMS8E RoHS-compliant Low Stress Injection Molded Plastic		100% matte Sn	MSL1 [2]	H272A XXXX	

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX

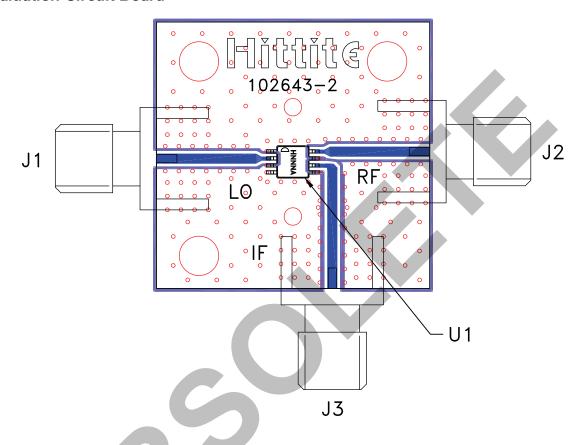


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Evaluation Circuit Board



List of Materials for Evaluation PCB 102781 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC272AMS8 / HMC272AMS8E Mixer
PCB [2]	102643 Evaluation Board

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350

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MAAM-009633-001SMB MASW-000936-001SMB 107712-HMC369LP3 107780-HMC322ALP4 SP000416870 EV1HMC470ALP3
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MAX2612EVKIT# MAX2692EVKIT# EV1HMC629ALP4E SKY12343-364LF-EVB 108703-HMC452QS16G EV1HMC863ALC4 119197HMC658LP2 EV1HMC647ALP6 ADL5725-EVALZ 106815-HMC441LM1 EV1HMC1018ALP4 UXN14M9PE MAX2016EVKIT
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